



Materials Declaration Form

IPC Form Type *	1752 Distribute	Version	2
Sectionals *	Material Info Manufacturing Info	Subsectionals *	A-D

** : Required Field*


Supplier Information			
Company Name *	STMicroelectronics	Response Date *	2015-09-14
Contact Name *	Refer to Supplier Comment section		Refer to Supplier Comment section
Authorized Representative *	Rossana Bonaccorso	Representative Title	IPD MD Champion
Representative Phone *	Refer to Supplier Comment section	Representative Email *	Refer to Supplier Comment section
Supplier Comment	Online Technical Support - STMicroelectronics : http://www.st.com/web/en/support/support.html		

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Legal Statement			
Supplier Acceptance *	true	Legal Declaration *	Standard
Legal Statement	<p>Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.</p>		

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
	8HZG*TWB201G	A	BOUSKOURA B/E	2015-09-14
Amount	UoM	Unit type	ST ECOPACK Grade	
98.00	mg	Each	ECOPACK2	

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles	 life.augmented	
1	260	3		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
NAC	Tin (Sn), matte	Copper Alloy		

Package Designator	Size	Nbr of instances	Shape	
SOJ	4.2, 3.7, 2.37	2	J BEND	
Comment	Package: SMB CLIP (SOD 6). Valid for CPs: SM6T200CA / SMBJ170CA-TR			

QueryList : ROHS directive 2011/65/EU _ July 2011	
Query	Response
1 - Product(s) meets EU RoHS requirement without any exemptions	false
2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	false
3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	true
4 - Product(s) does not meet EU RoHS requirements and is not under exemptions	false
5 - Product(s) is obsolete, no information is available	false
6 - Product(s) is unknown, no information is available	false
Exemption Id.	Description
7a	Lead in high melting temperature type solders (i.e. lead- based alloys containing 85 % by weight or more lead)

QueryList : REACH-15th June 2015				
Query				Response
1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				true
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product

Material Composition Declaration						Mfr Item Name	8HZG*TW8201G					
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
Die or Dies (choose)	Other inorganic materials	1.821	mg	supplier	die	Silicon (Si)	7440-21-3		1.789	mg	982427	18255
				supplier	metallization	Aluminium (Al)	7429-90-5		0.005	mg	2746	51
				supplier	Passivation	Silicon Oxide	7631-86-9		0.007	mg	3844	71
				supplier	back side metallization	Aluminium (Al)	7429-90-5		0.007	mg	3844	71
				supplier	back side metallization	Gold (Au)	7440-57-5		0.002	mg	1098	20
				supplier	back side metallization	Nickel (Ni)	7440-02-0		0.011	mg	6041	112
Leadframe	Copper & its alloys	40.676	mg	supplier	alloy	Copper (Cu)	7440-50-8		40.623	mg	998697	414520
				supplier	alloy	Iron (Fe)	7439-89-6		0.041	mg	1008	418
				supplier	alloy	Iron Phosphide (FeP)	26508-33-8		0.012	mg	295	122
Soft solder	Solder	1.760	mg	JIG - R	solder	Lead (Pb)	7439-92-1	7a-Lead in high me	1.646	mg	935227	16796
				supplier	solder	Tin (Sn)	7440-31-5		0.088	mg	50000	898
				supplier	solder	Silver (Ag)	7440-22-4		0.026	mg	14773	265
Encapsulation	Other Organic Materials	34.602	mg	supplier	mold compound	Silica, vitreous	60676-86-0		26.298	mg	760014	268347
				supplier	mold compound	Epoxy Cresol Novolak	29690-82-2		3.529	mg	101988	36010
				supplier	mold compound	Phenol resin	9003-35-4		2.076	mg	59997	21184
				supplier	mold compound	Others	Proprietary		1.730	mg	49997	17653
				supplier	mold compound	Metal hydroxide	21645-51-2		0.692	mg	19999	7061
				supplier	mold compound	Carbon black	1333-86-4		0.277	mg	8005	2827
Connections coating	Solder	0.811	mg	supplier	solder alloy	Tin (Sn)	7440-31-5		0.811	mg	1000000	8276
Clip	Copper & its alloys	18.330	mg	supplier	alloy	Copper (Cu)	7440-50-8		18.330	mg	1000000	187041